

Solder Joint Reliability Of BGA, CSP, Flip Chip, And Fine Pitch SMT Assemblies By John H. Lau

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solder joint reliability of cavity down plastic - plastic ball grid array (PBGA) assemblies. Stress analysis was performed to investigate the solder joint reliability assemblies, the outermost solder ball has

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chip scale package (csp) solder joint - J.H. Lau, Y-H. Pao; Solder Joint Reliability of BGA, CSP, Flip Chip, and Fine Pitch SMT Assemblies, J.H. Lau; Ball Grid Array Technology,

y. h.pao: solder joint reliability of bga (1997) - - Y.H.Pao: Solder Joint Reliability of BGA Venue: CSP, Flip Chip, and Fine Pitch SMT Assemblies cyclic stress and strain were accumulated in the solder joint

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solder joint reliability of bga, csp, flip chip, - This new volume by interconnection expert on solder joints, Johns H. Lau, deals with BGA, CSP, Flip Chips, and other new technologies that underlie the electronics

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